

Application Serial No. 10/642,936
Reply to office action of September 20, 2005

PATENT
Docket: CU-3332

REMARKS/ARGUMENTS

Reconsideration is respectfully requested.

Claims 1-5 and 9 are pending in the present application before this amendment. (Claims 6-8 have been withdrawn in response to an earlier restriction requirement.) By the present amendment, the withdrawn claims 6-8 have been cancelled without prejudice; and claim 1 has been amended. No new matter has been added.

In the office action, claims 1-2 and 4 stand rejected under 35 U.S.C. §103(a) as being obvious over U.S. Patent No. 3,642,597 (Sheldon) in view of U.S. Patent No. 5,904,546 (Wood).

In the office action, claim 9 is allowed.

Sheldon, as understood, discloses only a wafer dicing process by means of isotropic etching and scribing techniques. Wood, as understood, discloses only a wafer dicing process by means of anisotropic etching techniques.

Hence, these cited references do not disclose and/or suggest the execution order of isotropic and anisotropic etching steps of the presently claimed invention.

Also, Sheldon or Wood (individually or in combination) does not disclose or suggest that the same resist can be used to perform the isotropic etching and the anisotropic etching. Further, there is no disclosure and suggestion about the relationship between the width of the resist aperture and the width of grooves resulting from the isotropic and anisotropic etching.

According to the presently claimed invention, the step order and the width relation make it possible to form the rounded cutting surfaces (outer edge portions) of a semiconductor chip, thereby preventing an outer edge portion of the semiconductor chip

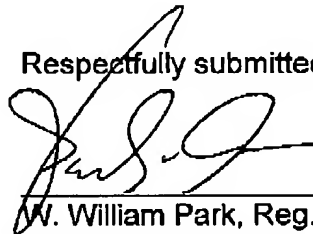
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from being chipped. These claimed subject matter, among others, are not taught or suggested by Sheldon, Wood, or other cited references whether they are considered individually or in combination.

For the reasons set forth above, the applicants respectfully submits that claims 1-5 and 9, now pending in this application, are either already allowed or in condition for allowance over the cited references. This amendment is considered to be responsive to all points raised in the office action. Accordingly, the applicant respectfully requests reconsideration and withdrawal of the outstanding rejections and earnestly solicits an indication of allowable subject matter.

Respectfully submitted,



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